<u>S/N 09/845881</u> <u>PATENT</u>

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Quat T. Vu et al. Examiner: Lourdes Cruz

Sectal No.: 09/845881 Group Art Unit: 2827 Filed: April 30, 2001 Docket: 884.384US1

Title: MICROELECTRONIC DEVICE HAVING SIGNAL DISTRIBUTION

FUNCTIONALITY ON AN INTERFACIAL LAYER THEREOF
Assignee: Intel Corporation Customer No: 21186

INFORMATION DISCLOSURE STATEMENT

Mail Stop RCE Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 *et. seq.*, the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicants respectfully request that this Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicants request that a copy of the 1449 form, initialed as being considered by the Examiner, be returned to the Applicants with the next official communication.

Applicants note that certain of the items of information contained in the Information Disclosure Statement were cited in International Search Reports in the following applications: PCT/US02/25089, PCT/US02/15802, and PCT/US02/12088. Copies of the relevant International Search Reports are enclosed.

Pursuant to 37 C.F.R. §1.97(b), it is believed that no fee or statement is required with the Information Disclosure Statement. However, if an Office Action on the merits has been mailed, the Commissioner is hereby authorized to charge the required fees to Deposit Account No. 19-0743 in order to have this Information Disclosure Statement considered.

INFORMATION DISCLOSURE STATEMENT

Page 2 Dkt: 884.384US1 (INTEL)

Serial No :09/845881

Filing Date: April 30, 2001

Title: MICROELECTRONIC DEVICE HAVING SIGNAL DISTRIBUTION FUNCTIONALITY ON AN INTERFACIAL LAYER THEREOF Assignee: Intel Corporation

The Examiner is invited to contact the Applicants' Representative at the below-listed telephone number if there are any questions regarding this communication.

Respectfully submitted,

QUAT T. VU ET AL.

By their Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

Attorneys for Intel Corporation

P.O. Box 2938

Minneapolis, Minnesota 55402

(612) 373-6969

Reg. No. 45,416

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this _____ day of December, 2003.

KACIA LEE

Signature Kacia Leo

PTO/SB/08A(10-01)
Approved for use through 10/31/2002. OMB 851-0031
US Patent & Trademark Office: U.S. DEPARTMENT OF COMMERCE

Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it contains a valid OMB control number Substitute for form 1449A/PTO Complete if Known INFORMATION DISCLOSURE 09/845881 **Application Number** STATEMENT BY APPLICANT Filing Date April 30, 2001 DEC 1 5 2003 **First Named Inventor** Vu, Quat 2827 **Group Art Unit** Cruz, Lourdes **Examiner Name** Attorney Docket No: 884.384US1 Sheet 1 of 2

	US PATENT DOCUMENTS						
Examiner Initial *	USP Document Number	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	Filing Date If Appropriate	
	US-2001/0013654	08/16/2001	Kalidas, N., et al.	257	738	12/22/1999	
	US-2002/0070443	06/13/2002	Mu, Xiao-Chun, et al.	257	712	12/08/2000	
	US-2002/0158334	10/31/2002	Vu, Quat T., et al.	257	723	04/30/2001	
	US-2002/0008314	01/24/2002	Takeuchi, Y.	257	697	04/13/2000	
	US-5,055,532	10/08/1991	Hoffman, Dwight K., et al.	525	528	07/06/1987	
	US-5,105,257	04/14/1992	Michii, K.	357	70	02/04/1991	
	US-5,355,283	10/11/1994	Marrs, Robert C., et al.	361	760	04/14/1993	
	US-5,523,622	06/04/1996	Harada, Takashi, et al.	257	734	09/25/1995	
	US-5,608,262	03/04/1997	Degani, Y., et al.	257	723	02/24/1995	
	US-5,701,032	12/23/1997	Fischer, P.J., et al.	257	692	11/02/1995	
	US-5,707,894	01/13/1998	Hsiao, Ming-Shan	437	209	10/27/1995	
	US-5,798,567	08/25/1998	Kelly, Michael G., et al.	257	723	08/21/1997	
	US-5,864,470	01/26/1999	Shim, I.K., et al.	361	777	06/25/1997	
	US-6,014,317	01/11/2000	Sylvester, Mark F.	361	760	03/18/1998	
	US-6,049,465	04/11/2000	Blish, II, Richard C., et al.	361	767	09/25/1998	
	US-6,060,777	05/09/2000	Jamieson, M P., et al.	257	707	07/21/1998	
	US-6,084,297	07/04/2000	Brooks, J. M., et al.	257	698	09/03/1998	
	US-6,084,777	07/04/2000	Kalidas, N., et al.	361	707	04/23/1998	
	US-6,130,478	10/10/2000	Dumoulin, A., et al.	257	728	04/18/1998	
	US-6,222,246	04/24/2001	Mak, T. M., et al.	257	532	01/08/1999	
	US-6,239,482	05/29/2001	Fillion, Raymond A., et al.	257	678	06/21/1999	
	US-6,388,333	05/14/2002	Taniguchi, F., et al.	257	777	06/27/2000	

		FOREIGN PA	ATENT DOCUMENTS			
Examiner Initials*	Foreign Document No	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	T ²
	EP-0149317	07/24/1985	Heeks, J. S., et al.	H05K	3/28	
	EP-0361825	04/04/1990	Misawa, H.	H01L	23/522	
	EP-0431205	06/12/1991	Schroeder, J. A.	H01L	23/498	
	EP-0476971	03/25/1992	Sakai, H , et al.	H01L	23/15	
	EP-0611129	08/17/1994	Fillion, R A., et al.	H01L	21/58	
	EP-0777274	06/04/1997	Wojnarowski, Robert J., et al.	H01L	23/538	
*****	EP-0877419	11/11/1998	Rinne, Glenn A., et al.	H01L	21/60	
	EP-1111662	06/27/2001	Saia, R J., et al.	H01L	21/00	
	GB-2174543	11/05/1986	Cognetti de Martiis, C	H01L	23/50	
	JP-10-125721	05/15/1998	Chikako, H.	H01L	21/60	
	JP-11-204688	07/30/1999	Kenji, A.	H01L	23/12	
	JP-2000-243870	09/08/2000	Akira, K.	H01L	23/12	
	JP-2000-307005	11/02/2000	Yasushi, T.	H01L	21/82	
	JP-2000-349203	12/15/2000	Kato, Chikayuki	H01L	23/28	

EXAMINER

DATE CONSIDERED

PTO/SB/08A(10-01)
Approved for use through 10/31/2002, OMB 651-0031
US Patent & Trademark Office: U.S. DEPARTMENT OF COMMERCE

Substitute for form 1449A/PTO INFORMATION DISCLOSURE **Application Number** 09/845881 STATEMENT BY APPLICANT:
(Use as many sheets as necessary April 30, 2001 **Filing Date** DEC 1 5 2003 **First Named Inventor** Vu, Quat 2827 **Group Art Unit** Cruz, Lourdes **Examiner Name** Attorney Docket No: 884.384US1 Sheet 2 of 2

FOREIGN PATENT DOCUMENTS							
Examiner Initials*	Foreign Document No	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	T ²	
	JP-62-004351	01/10/1987	Tamio, S	H01L	23/48		

	OTHE	R DOCUMENTS NON PATENT LITERATURE DOCUMENTS		
Examiner Initials*	Cite No 1	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.		
	Ì	CHEN, CHANG-LEE, et al., "Bond Wireless Multichip Packaging Technology for		
		High-Speed Circuits", IEEE Transactions on Components, Hybrids, and		
		Manufacturing Technology, 15, NY, US, (1992), 451-456		
		DAUM, W., et al., "Overlay High-Density Interconnect: A Chips-First Multichip		
		Module Technology", <u>IEEE Computer Society</u> , 26, Long Beach, CA, US, (1993), 23-29		
		GDULA, MICHAEL, et al., "An Overlay Interconnect Technology for 1GHz. and		
		Above MCMs", Proceedings of the Multi Chip Module Conference (MCMC),		
		Santa Cruz, US, (1992), 171-174		